

Attorney's Docket No.: \_\_\_\_\_

## DECLARATION, POWER OF ATTORNEY AND PETITION

I (We), the undersigned inventor(s), hereby declare that:

My residence, post office address and citizenship are as stated below next to my name,

I (We) believe that I am (we are) the original, first, and joint (sole) inventor(s) of the subject matter which is claimed and for which a patent is sought on the invention entitled

BEADS ALIGNMENT STRUCTURE, PRODUCTION METHOD THEREOF, AND BEAD  
ALIGNMENT METHOD FOR CAPILLARY BEADS ARRAY

the specification of which

☒ is attached hereto.

☐ was filed on \_\_\_\_\_ as

Application Serial No. \_\_\_\_\_

and amended on \_\_\_\_\_.

☐ was filed as PCT international application

Number \_\_\_\_\_

on \_\_\_\_\_,

and was amended under PCT Article 19

on \_\_\_\_\_ (if applicable).

I (We) hereby state that I (We) have reviewed and understand the contents of the above-identified specification, including the claims, as amended by any amendment referred to above; that I (We) do not know and do not believe that this invention was ever known or used before my invention or discovery thereof, or patented or described in any printed publication in any country before my invention or discovery thereof, or more than one year prior to this application, or in public use or on sale in the United States for more than one year prior to this application; that this invention or discovery has not been patented or made the subject of an inventor's certificate in any country foreign to the United States on an application filed by me or my legal representatives or assigns more than twelve months before this application.

I (We) acknowledge the duty to disclose information known to be material to the patentability of this application as defined in Section 1.56 of Title 37 Code of Federal Regulations.

I (We) hereby claim foreign priority benefits under Section 119(a)-(d) of Title 35 United States Code, of any foreign application(s) for patent or inventor's certificate listed below and have also identified below any foreign application for patent or inventor's certificate having a filing date before that of the application on which priority is claimed:

Application No.	Country	Filing date	Priority claimed	
<u>2003-113579</u>	<u>Japan</u>	<u>April 18, 2003</u>	<input checked="" type="checkbox"/> Yes	<input type="checkbox"/> No
<u>                    </u>	<u>                    </u>	<u>                    </u>	<input type="checkbox"/> Yes	<input type="checkbox"/> No
<u>                    </u>	<u>                    </u>	<u>                    </u>	<input type="checkbox"/> Yes	<input type="checkbox"/> No
<u>                    </u>	<u>                    </u>	<u>                    </u>	<input type="checkbox"/> Yes	<input type="checkbox"/> No

I hereby claim the benefit under Section 119(e) of Title 35 United States Code, of any United States application(s) listed below.

(Application Number)	(Filing Date)
(Application Number)	(Filing Date)

I (We) hereby claim the benefit under Section 120 of Title 35 United States Code, of any United States application(s) listed below and, insofar as the subject matter of each of the claims of this application is not disclosed in the prior United States application in the manner provided by the first paragraph of Section 112 of Title 35 United States Code, I (We) acknowledge the duty to disclose material information as defined in Section 1.56(a) of Title 37 Code of Federal Regulations, which occurred between the filing date of the prior application and national or PCT international filing date of this application:

Application Serial No.	Filing Date	Status (pending, patented, abandoned)
_____	_____	_____
_____	_____	_____

And I (We) hereby appoint: Stanley P. Fisher, Registration No. 24,344 and Juan Carlos Marquez, Registration No. 34,072.

I(We) hereby request that all correspondence regarding this application be sent to the firm of Reed Smith Hazel & Thomas LLP whose Post office address is: 3110 Fairview Park Drive, Suite 1400, Falls Church, Virginia 22042-4503 U.S.A.

I (We) declare further that all statements made herein of my (our) knowledge are true and that all statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under Section 1001 of Title 18 of the United States Code and that such willful false statements may jeopardize the validity of the application or any patent issued thereon.

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<u>January 6, 2004</u>	<u>4-12-7, Higashishinagawa,</u>
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